

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	18	("5027189" "5156998" "5198695" "5216278" "5770468" "5901901" "6134776" "6284573" "6391770").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:12
S2	5	die with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:15
S3	12	("3613001" "3746973" "3781681" "3803483" "4479088" "4486705" "4523144" "4719417" "4947114" "5059897").PN. OR ("5357192").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 13:15
S4	45	(dice chip die) with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:41
S5	45	S4 not S3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:16
S6	40	S4 not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:16
S7	59	wafer with integrated adj circuit adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:42
S8	25	wafer with IC adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:43

S9	857	wafer with device adj region	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:43
S10	175	S9 and metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/09 13:44
S11	12	("3613001" "3746973" "3781681" "3803483" "4479088" "4486705" "4523144" "4719417" "4947114" "5059897").PN. OR ("5357192").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 13:47
S12	2	("5357192").URPN.	USPAT	OR	ON	2005/08/09 13:47
S13	20	("5414297" "5559362" "5665655" "5698892").PN. OR ("5831330"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 14:05
S14	31	257/919	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 14:06
S15	14	("5024970" "5414297" "5530280" "5559362" "5665655" "5698892" "5772906" "5831330" "5891808").PN. OR ("6300223"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 14:29
S16	21	("4228581" "4356211" "4922326" "4976814" "5017512" "5024970" "5096855" "5136354" "5157001").PN. OR ("5665655"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/09 16:20
S36	38794	wafer with metal coating with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:47
S37	237	wafer with metal with (layer film coating) with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:49
S38	243	wafer with back with metallization	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:49

S39	8	wafer with back with metallization with thermal	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 07:58
S40	13	wafer with back with metallization with dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:14
S41	2	"6,853,070".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:15
S42	2	"6,717,267".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:38
S43	1261	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/10 10:41
S44	103	S43 and heat with lid	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:43
S45	142	S43 and heat near3 (sink spreader slung) and wire	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/10 10:43
S46	11	("20010008776" "20020175421" "20020195270" "5424573" "5616957" "5977626" "6414385" "6437984" "6608763" "6703698" "6734552").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 10:44
S47	31	("5705851" "5904497" "6002181" "6072239" "6177721" "6184580" "6198171").PN. OR ("6414385").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 10:45

S48	11	("20010008776" "20020175421" "20020195270" "5424573" "5616957" "5977626" "6414385" "6437984" "6608763" "6703698" "6734552").PN. OR ("6849940").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 10:46
S49	40	("5397917" "5583378" "5724230" "5726493" "5796038" "5854511" "5866943" "5886408" "5909056" "5926371" "6020637" "6046499").PN. OR ("6184580").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 11:22
S50	1	"6,853,070".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/10 11:23